

# MA2Q735 (MA735)

## Silicon epitaxial planar type

For high frequency rectification

### ■ Features

- Forward current (Average)  $I_{F(AV)} = 1$  A rectification is possible
- Reverse voltage  $V_R = 30$  V is guaranteed
- Automatic insertion with the emboss taping is possible

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Maximum peak reverse voltage	$V_{RM}$	30	V
Forward current (Average) *1	$I_{F(AV)}$	1	A
Non-repetitive peak forward surge current *2	$I_{FSM}$	30	A
Junction temperature	$T_j$	-40 to +125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +125	$^\circ\text{C}$

Note) \*1: Mounted on the printed circuit board (glass epoxy board)

\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

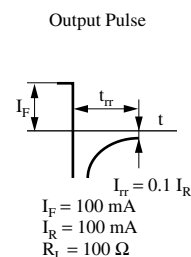
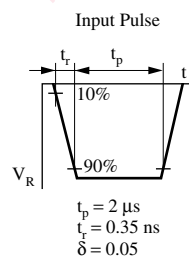
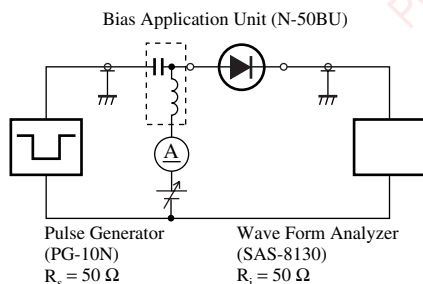
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 1.0$ A			0.5	V
Reverse current	$I_R$	$V_R = 30$ V			1	mA
Terminal capacitance	$C_t$	$V_R = 10$ V, $f = 1$ MHz		50		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 100$ mA $I_{tr} = 0.1 I_R$ , $R_L = 100 \Omega$			30	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

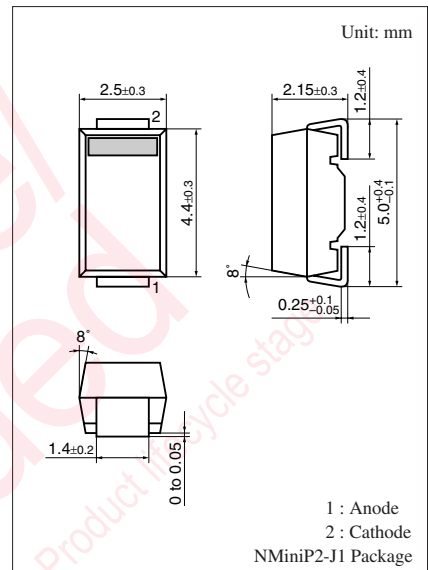
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

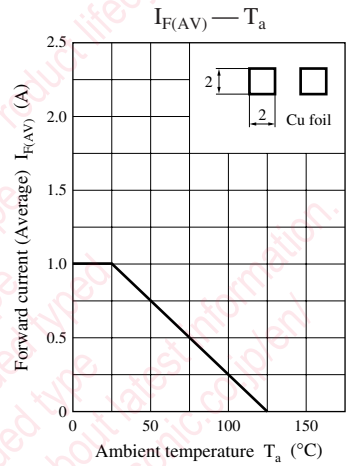
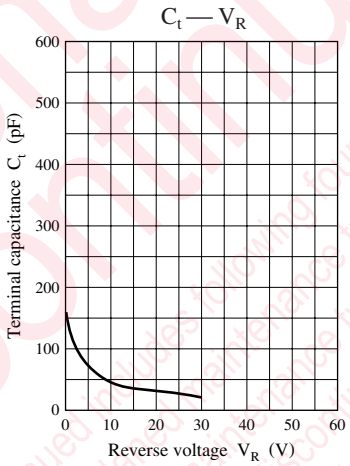
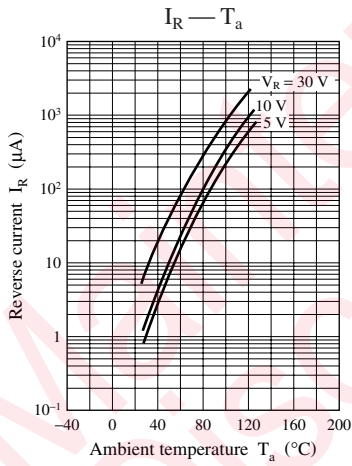
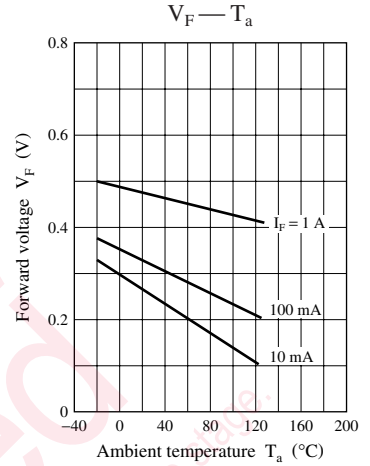
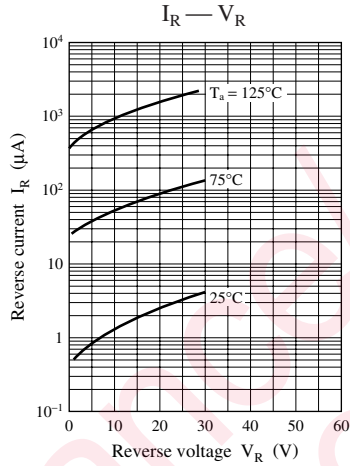
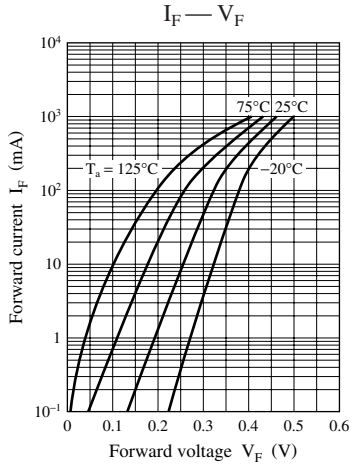
3. Absolute frequency of input and output is 20 MHz.

4. \*:  $t_{rr}$  measurement circuit



Marking Symbol: PA





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